[For High Quality and/or Reliability Equipment (Automotive / Industrial Equipment)]

Notice for TAIYO YUDEN Products

Please read this notice before using the TAIYO YUDEN products.

!\ REMINDERS

Product information in this catalog is as of October 2017. All of the contents specified herein are subject to change without notice due to technical improvements, etc. Therefore, please check for the latest information carefully before practical application or use of our products.

Please note that TAIYO YUDEN shall not be in any way responsible for any damages and defects in products or equipment incorporating our products, which are caused under the conditions other than those specified in this catalog or individual product specification sheets.

- Please contact TAIYO YUDEN for further details of product specifications as the individual product specification sheets are available.
- Please conduct validation and verification of our products in actual condition of mounting and operating environment before using our products.
- The products listed in this catalog are intended for use in general electronic equipment (e.g., AV equipment, OA equipment, home electric appliances, office equipment, information and communication equipment), medical equipment classified as Class I or II by IMDRF, industrial equipment, and automotive interior applications, etc. Please be sure to contact TAIYO YUDEN for further information before using the products for any equipment which may directly cause loss of human life or bodily injury (e.g., transportation equipment including, without limitation, automotive powertrain control system, train control system, and ship control system, traffic signal equipment, medical equipment classified as Class III by IMDRF).

Please do not incorporate our products into any equipment requiring high levels of safety and/or reliability (e.g., aerospace equipment, aviation equipment*, medical equipment classified as Class IV by IMDRF, nuclear control equipment, undersea equipment, military equipment).

*Note: There is a possibility that our products can be used only for aviation equipment that does not directly affect the safe operation of aircraft (e.g., in-flight entertainment, cabin light, electric seat, cooking equipment) if such use meets requirements specified separately by TAIYO YUDEN. Please be sure to contact TAIYO YUDEN for further information before using our products for such aviation equipment.

When our products are used even for high safety and/or reliability-required devices or circuits of general electronic equipment, it is strongly recommended to perform a thorough safety evaluation prior to use of our products and to install a protection circuit as necessary.

Please note that unless you obtain prior written consent of TAIYO YUDEN, TAIYO YUDEN shall not be in any way responsible for any damages incurred by you or third parties arising from use of the products listed in this catalog for any equipment requiring inquiry to TAIYO YUDEN or prohibited for use by TAIYO YUDEN as described above.

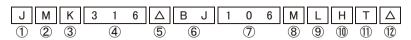
- Information contained in this catalog is intended to convey examples of typical performances and/or applications of our products and is not intended to make any warranty with respect to the intellectual property rights or any other related rights of TAIYO YUDEN or any third parties nor grant any license under such rights.
- Please note that the scope of warranty for our products is limited to the delivered our products themselves and TAIYO YUDEN shall not be in any way responsible for any damages resulting from a fault or defect in our products. Notwithstanding the foregoing, if there is a written agreement (e.g., supply and purchase agreement, quality assurance agreement) signed by TAIYO YUDEN and your company, TAIYO YUDEN will warrant our products in accordance with such agreement.
- The contents of this catalog are applicable to our products which are purchased from our sales offices or authorized distributors (hereinafter "TAIYO YUDEN's official sales channel"). Please note that the contents of this catalog are not applicable to our products purchased from any seller other than TAIYO YUDEN's official sales channel.
- Caution for Export
 Some of our products listed in this catalog may require specific procedures for export according to "U.S. Export Administration Regulations", "Foreign Exchange and Foreign Trade Control Law" of Japan, and other applicable regulations. Should you have any questions on this matter, please contact our sales staff.

MULTILAYER CERAMIC CAPACITORS





■PART NUMBER



△=Blank space

(1)	Rated	vo	ta	9.6

Code	Rated voltage[VDC]
Α	4
J	6.3
L	10
E	16
Т	25
G	35
U	50
Н	100
Q	250
S	630

Code	End termination
K	Plated
J	Soft Termination
S	Cu Internal Electrodes

3End termination

4 Dimension (L X	· VV)	
Type	Dimensions (L×W)[mm]	EIA (inch)
063	0.6 × 0.3	0201
105	1.0 × 0.5	0402
103	0.52 × 1.0 💥	0204
107	1.6 × 0.8	0603
	0.8 × 1.6 💥	0306
010	2.0 × 1.25	0805
212	1.25 × 2.0 💥	0508
316	3.2 × 1.6	1206
325	3.2 × 2.5	1210
432	4.5 × 3.2	1812
	4	

High Reliability Application

Note : $\mbox{\ensuremath{\,\raisebox{.4ex}{\times}}}\mbox{\ensuremath{\,\raisebox{.4e$

②Series name

<u> </u>	
Code	Series name
М	Multilayer ceramic capacitor
V	Multilayer ceramic capacitor for high frequency
W	LW reverse type multilayer capacitor

Code	Type	L[mm]	W[mm]	T[mm]
Δ	ALL	Standard	Standard	Standard
	063	0.6±0.05	0.3±0.05	0.3±0.05
	105	1.0±0.10	0.5±0.10	0.5±0.10
	107	1.6+0.15/-0.05	0.8+0.15/-0.05	0.8+0.15/-0.05
Α	212	2.0+0.15/-0.05	1.25+0.15/-0.05	0.85±0.10
	212	2.0+0.15/ -0.05	1.25+0.13/ -0.05	1.25+0.15/-0.05
	316	3.2±0.20	1.6±0.20	1.6±0.20
	325	3.2 ± 0.30	2.5±0.30	2.5±0.30
	105	1.0+0.15/-0.05	0.5+0.15/-0.05	0.5+0.15/-0.05
	107	1.6+0.20/-0	0.8+0.20/-0	0.8 + 0.20 / -0
В	212	2.0+0.20/-0	1.25+0.20/-0	0.85±0.10
				1.25+0.20/-0
	316	3.2±0.30	1.6±0.30	1.6±0.30
	105	1.0+0.20/-0	0.5+0.20/-0	0.5+0.20/-0
С	107	1.6+0.25/-0	0.8+0.25/-0	0.8+0.25/-0
	212	2.0+0.25/-0	1.25+0.25/-0	1.25+0.25/-0
	212	2.0±0.15	1.25±0.15	0.85±0.15
V	316	2.2.1.0.20	16+020	1.15±0.20
K	316	3.2±0.20	1.6±0.20	1.6±0.20
	325	3.2±0.50	2.5±0.30	2.5±0.30

Note: cf. STANDARD EXTERNAL DIMENSIONS

△= Blank space

6Temperature characteristics code

■ High dielectric type

Code		cable dard	Temperature range[°C]	Ref. Temp.[°C]	Capacitance change	Capacitance tolerance	Tolerance code
BJ	EIA	X5R	-55~+ 85	25	±15%	±10%	К
	EIA	YOK	-55/	20	±13%	±20%	М
C6	EIA	X6S	-55~+105	25	±22%	±10%	K
	LIA	A 703 33.4 103 23 ±2270	±20%	M			
В7	EIA	X7R	-55~+125	25	±15%	±10%	K
	LIA	X/IX	33.4 1 123	25	±13%	±20%	M
C7	EIA	X7S	-55~+125	25	±22%	±10%	K
	EIA	A/3	-55° +125	20	1 22 %	±20%	М
D7	EIA	X7T	-55~+125	25	+22%/-33%	±10%	K
	LIA	^/1	33.3 T 123	20	1 2270/ - 3370	±20%	M

[▶] This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our product specification sheets. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our website (http://www.ty-top.com/).

■Temperature compensating type

	- remperature compensating type							
	Code		icable idard	Temperature range[°C]	Ref. Temp.[°C]	Capacitance change	Capacitance tolerance	Tolerance code
							±0.1pF	В
		JIS C	CG		20	0.1.00	±0.25pF	С
	CG			-55~+125			±0.5pF	D
	CG			-55~+125	55~+125 0±30ppm/°C	±1pF	F	
		EIA	C0G		25	±2%	±2%	G
						±5%	J	

Nominal capacitance

Code (example)	Nominal capacitance
(example)	
0R5	0.5pF
010	1pF
100	10pF
101	100pF
102	1,000pF
103	0.01 µF
104	0.1 μF
105	1.0 <i>μ</i> F
106	10 <i>µ</i> F
107	100 μF

Note : R=Decimal point

8 Capacitance tolerance

Code	Capacitance tolerance
В	±0.1pF
С	±0.25pF
D	±0.5pF
G	±2%
J	±5%
K	±10%
М	±20%

Thickness

Code	Thickness[mm]
Р	0.3
Т	0.3
V	0.5
С	0.7(107type or more)
Α	0.8
D	0.85(212type or more)
F	1.15
G	1.25
L	1.6
N	1.9
М	2.5

®Special code

Code	Special code
Н	MLCC for Industrial and Automotive

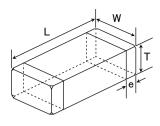
11)Packaging

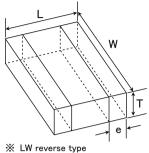
Code	Packaging
F	ϕ 178mm Taping (2mm pitch)
R	φ178mm Embossed Taping (4mm pitch)
Т	φ178mm Taping (4mm pitch)
P	φ178mm Taping (4mm pitch, 1000 pcs/reel)
Р	325 type (Thickness code M)

12Internal code

Elittorriar codo	
Code	Internal code
Δ	Standard

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T (514)		Dime	nsion [mm] (inch)		
Type(EIA)	L	W	Т	*1	е
□MK063(0201)	0.6±0.03 (0.024±0.001)	0.3±0.03 (0.012±0.001)	0.3±0.03 (0.012±0.001)	Т	0.15±0.05 (0.006±0.002)
□MK105(0402) □MF105(0402)	1.0±0.05 (0.039±0.002)	0.5±0.05 (0.020±0.002)	0.5±0.05 (0.020±0.002)	٧	0.25±0.10 (0.010±0.004)
□WK105(0204)※	0.52±0.05 (0.020±0.002)	1.0±0.05 (0.039±0.002)	0.3±0.05 (0.012±0.002)	Р	0.18±0.08 (0.007±0.003)
□MK107(0603) □MF107(0603)	1.6±0.10 (0.063±0.004)	0.8±0.10 (0.031±0.004)	0.8±0.10 (0.031±0.004)	Α	0.35±0.25 (0.014±0.010)
□MJ107(0603)	1.6±0.10 (0.063±0.004)	0.8±0.10 (0.031±0.004)	0.8±0.10 (0.031±0.004)	Α	0.35+0.3/-0.25 (0.014+0.012/-0.010)
□VS107(0603)	1.6±0.10 (0.063±0.004)	0.8±0.10 (0.031±0.004)	0.7±0.10 (0.028±0.004)	С	0.35±0.25 (0.014±0.010)
□WK107(0306)※	0.8±0.10 (0.031±0.004)	1.6±0.10 (0.063±0.004)	0.5±0.05 (0.020±0.002)	٧	0.25±0.15 (0.010±0.006)
□MK212(0805)	2.0±0.10	1.25±0.10	0.85±0.10 (0.033±0.004)	D	0.5±0.25
□MF212(0805)	(0.079 ± 0.004)	(0.049 ± 0.004)	1.25±0.10 (0.049±0.004)	G	(0.020±0.010)
	2.0±0.10	1.25±0.10	0.85±0.10 (0.033±0.004)	D	0.5+0.35/-0.25
□MJ212(0805)	(0.079 ± 0.004)	(0.049 ± 0.004)	±0.10 (0.033±0.004) ±0.004) 1.25±0.10 (0.049±0.004)		(0.020+0.014/-0.010)
□VS212(0805)	2.0±0.10 (0.079±0.004)	1.25±0.10 (0.049±0.004)	0.85±0.10 (0.033±0.004)	D	0.5±0.25 (0.020±0.010)
□WK212(0508)※	1.25±0.15 (0.049±0.006)	2.0±0.15 (0.079±0.006)	0.85±0.10 (0.033±0.004)	D	0.3±0.2 (0.012±0.008)
□MK316(1206)	3.2±0.15	1.6±0.15	1.15±0.10 (0.045±0.004)	F	0.5+0.35/-0.25
□MF316(1206)	(0.126±0.006)	(0.063±0.006)	1.6±0.20 (0.063±0.008)	L	(0.020+0.014/-0.010)
	3.2±0.15	1.6±0.15	1.15±0.10 (0.045±0.004)	F	0.6+0.4/-0.3
□MJ316(1206)	(0.126±0.006)	(0.063±0.006)	1.6±0.20 (0.063±0.008)	L	(0.024+0.016/-0.012)
			1.15±0.10 (0.045±0.004)	F	
□MK325(1210) □MF325(1210)	3.2±0.30 (0.126±0.012)	2.5±0.20 (0.098±0.008)	1.9±0.20 (0.075±0.008)	N	0.6±0.3 (0.024±0.012)
			2.5±0.20 (0.098±0.008)	М	
ΠM 100Ε (101C)	3.2±0.30	2.5±0.20	1.9±0.20 (0.075±0.008)	N	0.6+0.4/-0.3
□MJ325(1210)	(0.126±0.012)	(0.098±0.008)	2.5±0.20 (0.098±0.008)	М	(0.024+0.016/-0.012)

(0.177±0.016) (0.126 ± 0.012) Note : X. LW reverse type, *1.Thickness code

□MK432(1812)

4.5±0.40

 3.2 ± 0.30

2.5±0.20

 (0.098 ± 0.008)

М

0.9±0.6

 (0.035 ± 0.024)

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Туре	EIA (inch)	Dime	nsion	Standard qu	uantity[pcs]
Туре	EIA (Inch)	[mm]	Code	Paper tape	Embossed tape
063	0201	0.3	T	15000	_
105	0402	0.5	V	10000	
105	0204 ※	0.30	Р	10000	_
		0.7	С	4000	
		0.8	Α	4000	_
	0603	0.0	Δ.	3000	
107	0003	0.8	Α	(Soft Termination)	_
		0.8	Α	_	3000
		0.8	A	_	(Soft Termination)
	0306 ※	0.50	V	_	4000
		0.85	D	4000	_
	0005	1.25	G	_	3000
212	0805	1.05	0		2000
		1.25	G	_	(Soft Termination)
	0508 ※	0.85	D	4000	_
316	1206	1.15	F	_	3000
310	1200	1.6	L	_	2000
		1.15	F		2000
325	1210	1.9	N	_	2000
		2.5	М	_	500(T), 1000(P)
432	1812	2.5	М	_	500

Note : ※LW Reverse type(□WK)

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- · All the Multilayer Ceramic Capacitors of the catalog lineup are RoHS compliant.
- Capacitance tolerance code is applied to [] of part number.
- All the Multilayer Ceramic Capacitors in the catalog lineup are applicable for reflow-soldering.

Note

- The exchange of individual specifications is necessary depending on the application and circuit condition. Please contact Taiyo Yuden sales channels.
- * *1: Automotive (AEC-Q200 Qualified) products
 - < AEC-Q200 : AEC-Q200 qualified>

All the Multilayer Ceramic Capacitors of *1 marks are tested based on the test conditions and methods defined in AEC-Q200 by family item.

 $125^{\circ}C \quad \text{products:} \quad \text{AEC-Q200} \quad \text{Grade1} \quad \text{(we conduct the evaluation at the test condition of Grade1.)}$

 $105^{\circ}\text{C}\,$ products: AEC-Q200 Grade2 (we conduct the evaluation at the test condition of Grade2.)

85°C products: AEC-Q200 Grade3 (we conduct the evaluation at the test condition of Grade3.)

Please consult with TAIYO YUDEN's official sales channel for the details of the product specification and AEC-Q200 test results, etc.,

and please review and approve TAIYO YUDEN's product specification before ordering.

- *2: Industrial products and Medical products
- *3: For standard case size, please kindly refer to @Dimension, ⑤Dimension tolerance, ⑨Thickness and STANDARD EXTERNAL DIMENSIONS.

Multilayer Ceramic Capacitors (High dielectric type)

■105TYPE (Demension:1.0 × 0.5mm JIS:1005 EIA:0402)

[Temperature Characteristic BJ: X5R] 0.5mm thickness(V)

Part number 1	Part number 2	Rated voltage	Temperature	Capacitance	Capacitance	tan δ	HTLT	Thickness*3 [mm]	Note
		[V]	characteristics	[F]	tolerance [%]	[%]	Rated voltage x %		
JMK105 BJ102∏VHF			X5R	1000 p	±10, ±20	2.5	200	0.5±0.05	*1, *2
JMK105 BJ152∏VHF			X5R	1500 p	±10, ±20	2.5	200	0.5±0.05	*1, *2
JMK105 BJ222∏VHF			X5R	2200 p	$\pm 10, \pm 20$	2.5	200	0.5 ± 0.05	*1, *2
JMK105 BJ332∏VHF			X5R	3300 p	$\pm 10, \pm 20$	2.5	200	0.5 ± 0.05	*1, *2
JMK105 BJ472∏VHF		50	X5R	4700 p	$\pm 10, \pm 20$	2.5	200	0.5 ± 0.05	*1, *2
IMK105 BJ682∏VHF		- 50	X5R	6800 p	$\pm 10, \pm 20$	2.5	150	0.5 ± 0.05	*1, *2
MK105 BJ103∏VHF			X5R	0.01 μ	$\pm 10, \pm 20$	3.5	200	0.5 ± 0.05	*1, *2
MK105 BJ223∏VHF			X5R	0.022 μ	$\pm 10, \pm 20$	5	200	0.5 ± 0.05	*1, *2
MK105 BJ473∏VHF			X5R	0.047 μ	±10, ±20	5	200	0.5 ± 0.05	*1, *2
MK105 BJ104∏VHF			X5R	0.1 μ	±10, ±20	10	150	0.5 ± 0.05	*1, *2
MK105 BJ472[]VHF			X5R	4700 p	±10, ±20	2.5	200	0.5±0.05	*1, *2
MK105 BJ682∐VHF			X5R	6800 p	±10, ±20	2.5	200	0.5±0.05	*1, *2
MK105 BJ103[]VHF			X5R	0.01 μ	±10, ±20	3.5	200	0.5 ± 0.05	*1, *2
MK105 BJ223[]VHF		25	X5R	0.022 μ	±10, ±20	3.5	200	0.5 ± 0.05	*1, *2
MK105 BJ473[]VHF		25	X5R	0.047 μ	±10, ±20	3.5	150	0.5 ± 0.05	*1, *
MK105 BJ104[]VHF			X5R	0.1 μ	±10, ±20	5	150	0.5 ± 0.05	*1, *
MK105 BJ224[]VHF			X5R	0.22 μ	±10, ±20	10	150	0.5 ± 0.05	*1, *
MK105ABJ474[]VHF			X5R	0.47 μ	±10, ±20	10	150	0.5 ± 0.10	*1, *
MK105 BJ103[]VHF			X5R	0.01 μ	±10, ±20	3.5	200	0.5±0.05	*1, *
MK105 BJ223[]VHF			X5R	0.022 μ	±10, ±20	3.5	200	0.5 ± 0.05	*1, *;
MK105 BJ473[]VHF			X5R	0.047 μ	±10, ±20	3.5	150	0.5 ± 0.05	*1, *
MK105 BJ104[]VHF		16	X5R	0.1 μ	±10, ±20	5	150	0.5±0.05	*1, *
MK105 BJ224[]VHF			X5R	0.22 μ	±10, ±20	10	150	0.5 ± 0.05	*1, *
MK105ABJ474∏VHF			X5R	0.47 μ	±10, ±20	10	150	0.5±0.10	*1, *
MK105 BJ105 VHF			X5R	1 μ	±10, ±20	10	150	0.5 ± 0.05	*1, *
MK105 BJ473[]VHF			X5R	0.047 μ	±10, ±20	3.5	150	0.5 ± 0.05	*1, *
MK105 BJ104[]VHF			X5R	0.1 μ	±10, ±20	5	150	0.5 ± 0.05	*1, *
MK105 BJ224 VHF		- 10	X5R	0.22 μ	±10, ±20	5	150	0.5 ± 0.05	*1, *
MK105ABJ474[]VHF		10	X5R	0.47 μ	±10, ±20	10	150	0.5±0.10	*1, *
MK105 BJ105∏VHF		7	X5R	1 μ	±10, ±20	10	150	0.5±0.05	*1, *
MK105ABJ225[]VHF		╡ !	X5R	2.2 μ	±10, ±20	10	150	0.5±0.10	*1, *2
MK105 BJ104 VHF		1	X5R	0.1 μ	±10, ±20	5	150	0.5±0.05	*1, *
MK105 BJ224 VHF		╡ !	X5R	0.22 μ	±10, ±20	5	150	0.5±0.05	*1, *
MK105 BJ474 VHF		-	X5R	0.47 μ	±10, ±20	10	150	0.5±0.05	*1. *
MK105 BJ105∏VHF		6.3	X5R	1 μ	±10, ±20	10	150	0.5±0.05	*1. *
MK105 BJ225 VHF		┪ !	X5R	2.2 μ	±10, ±20	10	150	0.5±0.05	*1. *
MK105BBJ475MVHF		┪ !	X5R	4.7 μ	±20	10	150	0.5+0.15/-0.05	*1, *:
MK105 BJ225 \\ VHF			X5R	2.2 μ	±10, ±20	10	150	0.5±0.05	*1. *
MK105BBJ475MVHF		4	X5R	4.7 μ	±20	10	150	0.5+0.15/-0.05	*1. *
AMK105CBJ106MVHF		┥ '	X5R	10 μ	±20	10	150	0.5+0.20/-0	*1, *2

[Temperature Characteristic B7 : X7R] 0.5mm thickness(V)

Part number 1	Part number 2	Rated voltage [V]	Temper		Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT	Thickness*3 [mm]	Note
		[4]	Cilaiacte					Rated voltage x %		
UMK105 B7102 VHF				X7R	1000 p	±10, ±20	2.5	200	0.5 ± 0.05	*1, *2
UMK105 B7152□VHF				X7R	1500 p	±10, ±20	2.5	200	0.5 ± 0.05	*1, *2
UMK105 B7222 UHF				X7R	2200 p	±10, ±20	2.5	200	0.5 ± 0.05	*1, *2
UMK105 B7332 UHF				X7R	3300 p	$\pm 10, \pm 20$	2.5	200	0.5 ± 0.05	*1, *2
UMK105 B7472 UHF		50		X7R	4700 p	$\pm 10, \pm 20$	2.5	150	0.5 ± 0.05	*1, *2
UMK105 B7682 UHF		30		X7R	6800 p	±10, ±20	2.5	150	0.5 ± 0.05	*1, *2
UMK105 B7103 UHF				X7R	0.01 μ	±10, ±20	3.5	150	0.5 ± 0.05	*1, *2
UMK105 B7223 UHF				X7R	0.022 μ	±10, ±20	10	200	0.5 ± 0.05	*1, *2
UMK105 B7473 UHF				X7R	0.047 μ	±10, ±20	10	200	0.5 ± 0.05	*1, *2
UMK105 B7104 UHF				X7R	0.1 μ	±10, ±20	10	150	0.5 ± 0.05	*1, *2
TMK105 B7472 UHF				X7R	4700 p	±10, ±20	2.5	200	0.5 ± 0.05	*1, *2
TMK105 B7682 UHF				X7R	6800 p	±10, ±20	2.5	200	0.5 ± 0.05	*1, *2
TMK105 B7103 UHF		25		X7R	0.01 μ	±10, ±20	3.5	200	0.5 ± 0.05	*1, *2
TMK105 B7223 UHF		25		X7R	0.022 μ	±10, ±20	3.5	150	0.5 ± 0.05	*1, *2
TMK105 B7473 UHF				X7R	0.047 μ	±10, ±20	3.5	150	0.5 ± 0.05	*1, *2
TMK105 B7104 UHF				X7R	0.1 μ	±10, ±20	10	150	0.5 ± 0.05	*1, *2
EMK105 B7103[]VHF				X7R	0.01 μ	±10, ±20	3.5	200	0.5 ± 0.05	*1, *2
EMK105 B7223[]VHF		1		X7R	0.022 μ	±10, ±20	3.5	150	0.5 ± 0.05	*1, *2
EMK105 B7473 VHF		16		X7R	0.047 μ	±10, ±20	3.5	150	0.5 ± 0.05	*1, *2
EMK105 B7104[]VHF		1		X7R	0.1 μ	±10, ±20	5	150	0.5±0.05	*1, *2
EMK105 B7224 VHF		1		X7R	0.22 μ	±10, ±20	10	150	0.5 ± 0.05	*1, *2

[▶] This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our product specification sheets. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our website (http://www.ty-top.com/).

Part number 1	Part number 2	Rated voltage	Temperature	Capacitance	Capacitance	$ an\delta$	HTLT	Thickness*3 [mm]	Note
Fart number 1		[V]	characteristics	[F]	tolerance [%]	[%]	Rated voltage x %	THICKHESS [HIII]	Note
LMK105 B7473 UHF			X7R	0.047 μ	±10, ±20	3.5	150	0.5±0.05	*1, *2
LMK105 B7104 UHF		10	X7R	0.1 μ	±10, ±20	5	150	0.5±0.05	*1, *2
LMK105 B7224 UHF			X7R	0.22 μ	±10, ±20	10	150	0.5±0.05	*1, *2
JMK105 B7104 UHF			X7R	0.1 μ	±10, ±20	5	150	0.5±0.05	*1, *2
JMK105 B7224 UHF		6.3	X7R	0.22 μ	±10, ±20	10	150	0.5 ± 0.05	*1, *2
JMK105 B7474 UHF			X7R	0.47 μ	±10, ±20	10	150	0.5 ± 0.05	*1, *2
AMK105 B7474∏VHF		4	X7R	0.47 μ	±10, ±20	10	150	0.5 ± 0.05	*1. *2

●107TYPE (Dimension:1.6 × 0.8mm JIS:1608 EIA:0603)

 $\hbox{[Temperature Characteristic BJ:X5R]} \quad 0.8 mm \ thickness(A)$

Part number 1	Part number 2	Rated voltage	Temperature	Capacitance	Capacitance	$ an\delta$	HTLT	Thickness*3 [mm]	Note
Part number I	Part number 2	[V]	characteristics	[F]	tolerance [%]	[%]	Rated voltage x %	Inickness [mm]	Note
UMK107 BJ104[AHT			X5R	0.1 μ	±10, ±20	3.5	150	0.8±0.10	*1, *2
UMK107 BJ224[AHT		50	X5R	0.22 μ	±10, ±20	10	150	0.8±0.10	*1, *2
UMK107 BJ474∏AHT		50	X5R	0.47 μ	±10, ±20	10	150	0.8±0.10	*1, *2
UMK107ABJ105∏AHT			X5R	1 μ	±10, ±20	10	150	0.8+0.15/-0.05	*1, *2
GMK107 BJ223∏AHT			X5R	0.022 μ	±10, ±20	2.5	200	0.8±0.10	*1, *2
GMK107 BJ473[AHT			X5R	0.047 μ	±10, ±20	3.5	200	0.8±0.10	*1, *2
GMK107 BJ104[AHT		35	X5R	0.1 μ	±10, ±20	3.5	150	0.8±0.10	*1, *2
GMK107 BJ224∏AHT		33	X5R	0.22 μ	±10, ±20	10	150	0.8±0.10	*1, *2
GMK107ABJ474[]AHT			X5R	0.47 μ	±10, ±20	10	150	0.8+0.15/-0.05	*1, *2
GMK107 BJ105[AHT			X5R	1 μ	±10, ±20	10	150	0.8±0.10	*1, *2
TMK107 BJ223∏AHT			X5R	0.022 μ	±10, ±20	2.5	200	0.8±0.10	*1, *2
TMK107 BJ473∏AHT			X5R	0.047 μ	±10, ±20	3.5	200	0.8±0.10	*1, *2
TMK107 BJ104∏AHT			X5R	0.1 μ	±10, ±20	3.5	150	0.8±0.10	*1, *2
TMK107 BJ224∏AHT		25	X5R	0.22 μ	±10, ±20	5	150	0.8±0.10	*1, *2
TMK107 BJ474∏AHT			X5R	0.47 μ	±10, ±20	3.5	150	0.8±0.10	*1, *2
TMK107 BJ105∏AHT			X5R	1 μ	±10, ±20	10	150	0.8±0.10	*1, *2
TMK107BBJ225[]AHT			X5R	2.2 μ	±10, ±20	10	150	0.8+0.20/-0	*1, *2
EMK107 BJ104∏AHT			X5R	0.1 μ	±10, ±20	3.5	150	0.8±0.10	*1, *2
EMK107 BJ224∏AHT			X5R	0.22 μ	±10, ±20	5	150	0.8±0.10	*1, *2
EMK107 BJ474∏AHT		16	X5R	0.47 μ	±10, ±20	3.5	150	0.8±0.10	*1, *2
EMK107 BJ105∏AHT		10	X5R	1 μ	±10, ±20	5	150	0.8±0.10	*1, *2
EMK107ABJ225∏AHT			X5R	2.2 μ	±10, ±20	10	150	0.8+0.15/-0.05	*1, *2
EMK107BBJ475∏AHT			X5R	4.7 μ	±10, ±20	10	150	0.8+0.20/-0	*1, *2
LMK107 BJ474∏AHT			X5R	0.47 μ	±10, ±20	3.5	150	0.8±0.10	*1, *2
LMK107 BJ105∏AHT			X5R	1 μ	±10, ±20	5	150	0.8±0.10	*1, *2
LMK107 BJ225∏AHT		10	X5R	2.2 μ	±10, ±20	10	150	0.8±0.10	*1, *2
LMK107 BJ475∏AHT			X5R	4.7 μ	±10, ±20	10	150	0.8±0.10	*1, *2
LMK107BBJ106MAHT			X5R	10 μ	±20	10	150	0.8+0.20/-0	*1, *2
JMK107 BJ105∏AHT			X5R	1 μ	±10, ±20	5	150	0.8±0.10	*1, *2
JMK107 BJ225∏AHT		6.3	X5R	2.2 μ	±10, ±20	10	150	0.8±0.10	*1, *2
JMK107 BJ475∏AHT		0.3	X5R	4.7 μ	±10, ±20	10	150	0.8±0.10	*1, *2
JMK107ABJ106∏AHT			X5R	10 μ	±10, ±20	10	150	0.8+0.15/-0.05	*1, *2
AMK107ABJ106[AHT		4	X5R	10 μ	±10, ±20	10	150	0.8+0.15/-0.05	*1, *2
AMK107BBJ226MAHT		4	X5R	22 μ	±20	10	150	0.8+0.20/-0	*1, *2

Temperature Characteris	tic B7 : X7R , C7 : X7S ,	D7 : X7T】 0.8mi	m thickness(A)						
Part number 1	Part number 2	Rated voltage	Temperature	Capacitance	Capacitance	tan δ	HTLT	Thickness*3 [mm]	Note
r dre ridinber 1	T di Citambol 2	[V]	characteristics	[F]	tolerance [%]	[%]	Rated voltage x %	THICKIESS [IIIII]	14000
UMK107 B7102∏AHT			X7R	1000 p	±10, ±20	3.5	200	0.8 ± 0.10	*1, *2
UMK107 B7152□AHT			X7R	1500 p	±10, ±20	3.5	200	0.8 ± 0.10	*1, *2
UMK107 B7222[]AHT			X7R	2200 p	±10, ±20	3.5	200	0.8 ± 0.10	*1, *2
UMK107 B7332□AHT			X7R	3300 p	±10, ±20	3.5	200	0.8 ± 0.10	*1, *2
UMK107 B7472[AHT			X7R	4700 p	±10, ±20	3.5	200	0.8 ± 0.10	*1, *2
UMK107 B7682[]AHT		50	X7R	6800 p	±10, ±20	3.5	200	0.8 ± 0.10	*1, *2
UMK107 B7103[AHT			X7R	0.01 μ	±10, ±20	3.5	200	0.8 ± 0.10	*1, *2
UMK107 B7223 AHT			X7R	0.022 μ	±10, ±20	3.5	200	0.8 ± 0.10	*1, *2
UMK107 B7473 AHT			X7R	0.047 μ	±10, ±20	3.5	200	0.8 ± 0.10	*1, *2
UMK107 B7104[]AHT			X7R	0.1 μ	±10, ±20	3.5	200	0.8 ± 0.10	*1, *2
UMK107 C7224 AHTE			X7S	0.22 μ	±10, ±20	3.5	150	0.8 ± 0.10	*1, *2
GMK107 B7473∏AHT			X7R	0.047μ	$\pm 10, \pm 20$	3.5	200	0.8 ± 0.10	*1, *2
GMK107 B7104□AHT			X7R	0.1 μ	±10, ±20	3.5	150	0.8 ± 0.10	*1, *2
GMK107 B7224[]AHT		35	X7R	0.22 μ	±10, ±20	10	150	0.8 ± 0.10	*1, *2
GMK107 B7474□AHT			X7R	0.47 μ	±10, ±20	10	150	0.8 ± 0.10	*1, *2
GMK107AB7105∏AHT			X7R	1 μ	±10, ±20	10	150	0.8+0.15/-0.05	*1, *2
TMK107 B7223[AHT			X7R	0.022 μ	$\pm 10, \pm 20$	2.5	200	0.8 ± 0.10	*1, *2
TMK107 B7473[AHT			X7R	0.047 μ	$\pm 10, \pm 20$	3.5	200	0.8 ± 0.10	*1, *2
TMK107 B7104[]AHT		25	X7R	0.1 μ	$\pm 10, \pm 20$	3.5	150	0.8 ± 0.10	*1, *2
TMK107 B7224[]AHT		2.5	X7R	0.22 μ	±10, ±20	10	150	0.8 ± 0.10	*1, *2
TMK107 B7474[]AHT			X7R	0.47 μ	±10, ±20	10	150	0.8 ± 0.10	*1, *2
TMK107AB7105□AHT			X7R	1 μ	±10, ±20	10	150	0.8+0.15/-0.05	*1, *2
EMK107 B7473[]AHT			X7R	0.047 μ	±10, ±20	3.5	200	0.8 ± 0.10	*1, *2
EMK107 B7104[]AHT			X7R	0.1 μ	±10, ±20	3.5	150	0.8 ± 0.10	*1, *2
EMK107 B7224[]AHT		16	X7R	0.22 μ	±10, ±20	5	150	0.8 ± 0.10	*1, *2
EMK107 B7474[]AHT			X7R	0.47 μ	$\pm 10, \pm 20$	10	150	0.8 ± 0.10	*1, *2
EMK107 B7105[]AHT			X7R	1 μ	±10, ±20	10	150	0.8 ± 0.10	*1, *2
LMK107 B7224[]AHT			X7R	0.22 μ	±10, ±20	5	150	0.8 ± 0.10	*1, *2
LMK107 B7474[]AHT		10	X7R	0.47 μ	±10, ±20	3.5	150	0.8 ± 0.10	*1, *2
LMK107 B7105[]AHT		10	X7R	1 μ	±10, ±20	10	150	0.8 ± 0.10	*1, *2
LMK107BD7225[]AHT			X7T	2.2 μ	±10, ±20	10	200	0.8+0.20/-0	*1, *2
JMK107 B7105∏AHT		6.3	X7R	1 μ	±10, ±20	10	150	0.8±0.10	*1, *2
JMK107 B7225∏AHTR		0.3	X7R	2.2 μ	±10, ±20	10	150	0.8±0.10	*1, *2

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JMK212BBJ226MGHT

AMK212ABJ226MGHT

AMK212BBJ476MGHT

212TYPE (Dimension:2.0 × 1.25mm JIS:2012 EIA:0805)

[Temperature Characteristic BJ : X5R] 1.25mm thickness(G) Capacitance tolerance [%] HTLT tan δ [%] Part number 2 Thickness*3 [mm] Note characteristics Rated voltage x UMK212 BJ104[]GHT X5R 0.1 μ ±10, ±20 200 1.25±0.10 *1, *2 3.5 UMK212 BJ224[]GHT X5R 0.22 μ ±10, ±20 3.5 200 1.25±0.10 *1. *2 50 UMK212 BJ474∏GHT X5R 0.47 11 $\pm 10. \pm 20$ 3.5 150 1.25 ± 0.10 *1 *2 UMK212 BJ105[]GHT X5R 150 1.25±0.10 *1. *2 1 u $\pm 10. \pm 20$ GMK212 BJ104[]GHT X5R 0.1 μ ±10, ±20 3.5 200 1.25±0.10 *1, *2 GMK212 BJ224 GHT X5R 0.22 μ ±10, ±20 150 1.25±0.10 *1, *2 35 GMK212 BJ474∏GHT X5R 0.47 11 ±10, ±20 3.5 150 1.25±0.10 *1. *2 GMK212 BJ105∏GHT X5R 1 11 $\pm 10, \pm 20$ 150 1.25 ± 0.10 *1. *2 X5R 10 150 GMK212BBJ225 GHT 2.2 μ ±10, ±20 1.25+0.20/-0 *1, *2 X5R X5R ±10, ±20 TMK212 BJ104 GHT 0.1 μ 200 1.25±0.10 *1, *2 ±10. ±20 3.5 1.25±0.10 TMK212 BJ224∏GHT 0.22 11 150 *1 *2 TMK212 BJ474∏GHT X5R 0.47 μ $\pm 10. \pm 20$ 35 200 125+010 *1 *2 TMK212 BJ105∏GHT X5R ±10, ±20 3.5 150 1.25 ± 0.10 *1. *2 1 u TMK212 BJ225 GHT X5R ±10, ±20 150 1.25±0.10 *1, *2 2.2 μ X5R X5R TMK212BBJ475[]GHT 4.7 µ ±10, ±20 10 150 1.25+0.20/-0 *1 *2 TMK212BBJ106∏GHT 10 // +10 + 2010 150 1 25+0 20/-0 *1 *2 3.5 EMK212 BJ105 GHT X5R ±10, ±20 150 1.25±0.10 *1. *2 1 u 2.2 μ EMK212 BJ225 GHT X5R ±10, ±20 5 150 1.25±0.10 *1, *2 16 4.7 μ EMK212ABJ475[]GHT X5R ±10, ±20 10 150 1.25+0.15/-0.05 *1, *2 EMK212BBJ106[]GHT X5R 10 *u* $\pm 10, \pm 20$ 10 150 1.25+0.20/-0 *1. *2 LMK212 BJ225∏GHT X5R 2.2 11 $\pm 10. \pm 20$ 5 200 1.25 ± 0.10 *1. *2 10 X5R 10 LMK212ABJ475[]GHT 4.7 μ ±10, ±20 150 1.25+0.15/-0.05 *1, *2 X5R X5R 10 μ ±10, ±20 ±10, ±20 1.25+0.15/-0.05 1.25+0.15/-0.05 LMK212ABJ106[]GHT 10 150 *1. *2 JMK212ABJ475 GHT 4.7 II 200 *1. *2 JMK212ABJ106∏GHT 6.3 X5R 10 1.25+0.15/-0.05 10 μ $\pm 10. \pm 20$ 150 *1. *2

[Temperature Characteristic BJ : X5R] 0.85mm thickness(D)

Part number 1	Part number 2	Rated voltage [V]	Temperature characteristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Note
EMK212 BJ105∏DHT			X5R	1 μ	±10, ±20	5	200	0.85 ± 0.10	*1, *2
EMK212ABJ225□DHT		16	X5R	2.2 μ	±10, ±20	5	150	0.85 ± 0.10	*1, *2
EMK212BBJ475 DHT			X5R	4.7 μ	±10, ±20	10	150	0.85 ± 0.10	*1, *2

22 u

22 μ

10

10

 ± 20

±20

±20

150

150

150

1.25+0.20/-0

1.25+0.15/-0.05

1.25+0.20/-0

*1, *2

X5R

X5R

X5R

[Temperature Characteristic B7 : X7R] 1.25mm thickness(G)

Part number 1	Part number 2	Rated voltage [V]	Temper		Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT	Thickness*3 [mm]	Note
_		[4]	Characte					Rated voltage x %		
UMK212 B7103[]GHT				X7R	0.01 μ	±10, ±20	3.5	200	1.25±0.10	*1, *2
UMK212 B7223∏GHT				X7R	0.022 μ	±10, ±20	3.5	200	1.25±0.10	*1, *2
UMK212 B7473 GHT		50		X7R	0.047 μ	$\pm 10, \pm 20$	3.5	200	1.25±0.10	*1, *2
UMK212 B7104∏GHT		30		X7R	0.1 μ	$\pm 10, \pm 20$	3.5	200	1.25±0.10	*1, *2
UMK212 B7224 GHT				X7R	0.22 μ	$\pm 10, \pm 20$	3.5	150	1.25 ± 0.10	*1, *2
UMK212 B7105 GHT				X7R	1 μ	$\pm 10, \pm 20$	10	150	1.25±0.10	*1, *2
GMK212 B7224 GHT		35		X7R	0.22 μ	±10, ±20	3.5	150	1.25±0.10	*1, *2
GMK212 B7105 GHT		33		X7R	1 μ	±10, ±20	10	150	1.25±0.10	*1, *2
TMK212 B7224 GHT				X7R	0.22 μ	±10, ±20	3.5	150	1.25±0.10	*1, *2
TMK212 B7474[]GHT		25		X7R	0.47 μ	±10, ±20	3.5	150	1.25±0.10	*1, *2
TMK212 B7105[]GHTR		25		X7R	1 μ	±10, ±20	10	150	1.25±0.10	*1, *2
TMK212 B7225[]GHT				X7R	2.2 μ	±10, ±20	10	150	1.25±0.10	*1, *2
EMK212 B7224[]GHT				X7R	0.22 μ	±10, ±20	3.5	200	1.25±0.10	*1, *2
EMK212 B7474[]GHT				X7R	0.47 μ	±10, ±20	3.5	200	1.25±0.10	*1, *2
EMK212 B7105[]GHTR		16		X7R	1 μ	±10, ±20	10	150	1.25±0.10	*1, *2
EMK212 B7225[]GHT				X7R	2.2 μ	±10, ±20	10	150	1.25±0.10	*1, *2
EMK212AB7475[]GHT				X7R	4.7 μ	±10, ±20	10	150	1.25+0.15/-0.05	*1, *2
LMK212 B7105[]GHTR			ĺ	X7R	1 μ	±10, ±20	10	150	1.25±0.10	*1, *2
LMK212 B7225[]GHT		10		X7R	2.2 μ	±10, ±20	10	150	1.25±0.10	*1, *2
LMK212 B7475[]GHT		1		X7R	4.7 μ	±10, ±20	10	150	1.25±0.10	*1, *2
JMK212 B7475[]GHT		6.3	ĺ	X7R	4.7 μ	±10, ±20	10	150	1.25±0.10	*1, *2
JMK212AB7106□GHT		0.3		X7R	10 μ	±10, ±20	10	150	1.25+0.15/-0.05	*1, *2

■316TYPE (Dimension:3.2 × 1.6mm JIS:3216 EIA:1206)

[Temperature Characteristic BJ : X5R] 1.6mm thickness(L)

Part number 1	Part number 2	Rated voltage	Temperature	Capacitance	Capacitance	$ an\delta$	HTLT	Thickness*3 [mm]	Note
Part number 1	Part number 2	[V]	characteristics	[F]	tolerance [%]	[%]	Rated voltage x %	Inickness [mm]	Note
UMK316 BJ474[]LHT			X5R	0.47 μ	±10, ±20	3.5	200	1.6±0.20	*1, *2
UMK316 BJ105□LHT		50	X5R	1 μ	±10, ±20	3.5	200	1.6±0.20	*1, *2
UMK316 BJ225[]LHT		30	X5R	2.2 μ	±10, ±20	10	150	1.6±0.20	*1, *2
UMK316ABJ475[]LHT			X5R	4.7 μ	±10, ±20	10	150	1.6±0.20	*1, *2
GMK316 BJ105□LHT			X5R	1 μ	±10, ±20	3.5	200	1.6±0.20	*1, *2
GMK316 BJ225□LHT		35	X5R	2.2 μ	±10, ±20	10	150	1.6±0.20	*1, *2
GMK316 BJ475□LHT		33	X5R	4.7 μ	±10, ±20	10	150	1.6±0.20	*1, *2
GMK316BBJ106□LHT			X5R	10 μ	±10, ±20	10	150	1.6±0.30	*1, *2
TMK316 BJ225[LHT			X5R	2.2 μ	±10, ±20	3.5	200	1.6±0.20	*1, *2
TMK316 BJ475[LHT		25	X5R	4.7 μ	±10, ±20	5	150	1.6±0.20	*1, *2
TMK316 BJ106 LHT			X5R	10 μ	±10, ±20	5	150	1.6±0.20	*1, *2
EMK316 BJ225 LHT			X5R	2.2 μ	±10, ±20	3.5	200	1.6±0.20	*1, *2
EMK316 BJ475[]LHT		16	X5R	4.7 μ	±10, ±20	5	150	1.6±0.20	*1, *2
EMK316 BJ106[LHT		10	X5R	10 μ	±10, ±20	5	150	1.6±0.20	*1, *2
EMK316BBJ226MLHT			X5R	22 μ	±20	10	150	1.6±0.30	*1, *2
LMK316 BJ475[]LHT			X5R	4.7 μ	±10, ±20	5	150	1.6±0.20	*1, *2
LMK316 BJ106[LHT		10	X5R	10 μ	±10, ±20	5	150	1.6±0.20	*1, *2
LMK316ABJ226 LHT			X5R	22 μ	±10, ±20	10	150	1.6±0.20	*1, *2

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Part number 1	Part number 2	Rated voltage [V]	Tempe charact	erature teristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Note
JMK316 BJ106□LHT				X5R	10 μ	±10, ±20	5	200	1.6±0.20	*1, *2
JMK316ABJ226□LHT		6.3		X5R	22 μ	±10, ±20	10	150	1.6±0.20	*1, *2
JMK316ABJ476MLHT		0.3		X5R	47 μ	±20	10	150	1.6±0.20	*1, *2
JMK316BBJ107MLHT				X5R	100 μ	±20	10	150	1.6±0.30	*2
AMK316ABJ107MLHT		4		X5R	100 μ	±20	10	150	1.6±0.20	*2

【Temperature Characteristic B7 : X7R , C7 : X7S】 1.6mm thickness(L)

Part number 1	Part number 2	Rated voltage [V]	Tempe charact		Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Note
UMK316 B7473[]LHT				X7R	0.047 μ	±10, ±20	3.5	200	1.6±0.20	*1, *2
UMK316 B7104[]LHT				X7R	0.1 μ	±10, ±20	3.5	200	1.6±0.20	*1, *2
UMK316 B7224[]LHT				X7R	0.22 μ	±10, ±20	3.5	200	1.6±0.20	*1, *2
UMK316 B7474[]LHT		50		X7R	0.47 μ	$\pm 10, \pm 20$	3.5	200	1.6±0.20	*1, *2
UMK316 B7105[]LHT				X7R	1 μ	$\pm 10, \pm 20$	3.5	200	1.6±0.20	*1, *2
UMK316 B7225[]LHT				X7R	2.2 μ	±10, ±20	10	150	1.6±0.20	*1, *2
UMK316AC7475[LHTE				X7S	4.7 μ	±10, ±20	2.5	150	1.6±0.20	*1, *2
GMK316 B7105[]LHT				X7R	1 μ	±10, ±20	3.5	200	1.6±0.20	*1, *2
GMK316 B7225[]LHT		35		X7R	2.2 μ	$\pm 10, \pm 20$	10	150	1.6±0.20	*1, *2
GMK316AB7475[]LHT				X7R	4.7 μ	±10, ±20	10	150	1.6±0.20	*1, *2
TMK316 B7105[LHT				X7R	1 μ	$\pm 10, \pm 20$	3.5	200	1.6±0.20	*1, *2
TMK316 B7225 LHT		25		X7R	2.2 μ	$\pm 10, \pm 20$	3.5	200	1.6±0.20	*1, *2
TMK316AB7475[]LHT		2.5		X7R	4.7 μ	±10, ±20	10	150	1.6±0.20	*1, *2
TMK316AB7106[LHT				X7R	10 μ	±10, ±20	10	150	1.6±0.20	*1, *2
EMK316 B7225 LHT				X7R	2.2 μ	$\pm 10, \pm 20$	3.5	200	1.6±0.20	*1, *2
EMK316AB7475[]LHT		16		X7R	4.7 μ	±10, ±20	10	150	1.6±0.20	*1, *2
EMK316AB7106[LHT				X7R	10 μ	±10, ±20	10	150	1.6±0.20	*1, *2
LMK316 B7475□LHT		10		X7R	4.7 μ	$\pm 10, \pm 20$	5	150	1.6±0.20	*1, *2
LMK316AB7106 LHT		10		X7R	10 μ	±10, ±20	10	150	1.6±0.20	*1, *2
JMK316AB7106□LHT		6.3		X7R	10 μ	±10, ±20	10	150	1.6±0.20	*1, *2
JMK316AB7226□LHT		0.3		X7R	22 μ	±10, ±20	10	150	1.6±0.20	*1, *2
AMK316AB7226[]LHT		4		X7R	22 μ	±10, ±20	10	150	1.6±0.20	*1, *2
AMK316AC7476MLHT		4		X7S	47 μ	±20	10	150	1.6±0.20	*1, *2

●325TYPE (Dimension:3.2 × 2.5mm JIS:3225 EIA:1210)

[Temperature Characteristic BJ : X5R] 2.5mm thickness (M)

Part number 1	Part number 2	Rated voltage	Temperature	Capacitance	Capacitance	$ an\delta$	HTLT	Thickness*3 [mm]	Note
Part number 1	Part number 2	[V]	characteristics	[F]	tolerance [%]	[%]	Rated voltage x %	Inickness [mm]	Note
UMK325 BJ106∏MHP		50	X5R	10 μ	±10, ±20	5	150	2.5±0.20	*1, *2
GMK325 BJ106□MHP		35	X5R	10 μ	±10, ±20	5	150	2.5±0.20	*1, *2
TMK325 BJ106□MHP		25	X5R	10 μ	±10, ±20	5	150	2.5±0.20	*1, *2
EMK325 BJ226 MHP		16	X5R	22 μ	±10, ±20	5	150	2.5±0.20	*1, *2
EMK325ABJ476∏MHP		10	X5R	47 μ	±10, ±20	10	150	2.5±0.30	*1, *2
LMK325 BJ226 MHP			X5R	22 μ	±10, ±20	5	150	2.5±0.20	*1, *2
LMK325 BJ476 MHP		10	X5R	47 μ	±10, ±20	10	150	2.5±0.20	*1, *2
LMK325ABJ107MMHP			X5R	100 μ	±20	10	150	2.5±0.30	*2
JMK325 BJ476∏MHP		6.3	X5R	47 μ	±10, ±20	10	150	2.5±0.20	*1, *2
JMK325ABJ107MMHP		0.3	X5R	100 μ	±20	10	150	2.5±0.30	*2
AMK325ABJ107MMHP		4	X5R	100 μ	±20	10	150	2.5±0.30	*2
AMK325ABJ227MMHP		4	X5R	220 μ	±20	10	150	2.5±0.30	*2

[Temperature Characteristic BJ : X5R] 1.9mm thickness(N)

Part number 1	Part number 2	Rated voltage [V]	Tempe charact		Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Note
UMK325 BJ475[NHT		50		X5R	4.7 μ	±10, ±20	10	150	1.9±0.20	*1, *2
GMK325 BJ225MNHT		35		X5R	2.2 μ	±20	3.5	200	1.9±0.20	*1, *2
GMK325 BJ475□NHT		33		X5R	4.7 μ	$\pm 10, \pm 20$	10	150	1.9±0.20	*1, *2
TMK325 BJ475[NHT		25		X5R	4.7 μ	$\pm 10, \pm 20$	10	150	1.9±0.20	*1, *2
EMK325 BJ475MNHT		16		X5R	4.7 μ	±20	3.5	200	1.9±0.20	*1, *2
EMK325 BJ106□NHT		10		X5R	10 μ	$\pm 10, \pm 20$	5	150	1.9±0.20	*1, *2

Temperature Characteristic C6 : X6S] 2.5mm thickness (M)

Part number 1	Part number 2	Rated voltage [V]	Temper characte		Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Note
JMK325AC6107MMHP		6.3		X6S	100 //	+20	10	150	25+030	*2

[Temperature Characteristic B7 : X7R] 2.5mm thickness(M)

Temperature Characteris	CC D7 : A/R 1 2.5mm tri	CKriess (IVI)								
Part number 1	Part number 2	Rated voltage	Tempe	rature	Capacitance	Capacitance	$ an\delta$	HTLT	Thickness*3 [mm]	Note
rant number i	Fart number 2	[V]	charact	eristics	[F]	tolerance [%]	[%]	Rated voltage x %	Inickness [mm]	Note
UMK325 B7475[]MHP		50		X7R	4.7 μ	±10, ±20	5	150	2.5±0.20	*1, *2
UMK325AB7106[]MHP		30		X7R	10 μ	±10, ±20	10	150	2.5±0.30	*1, *2
GMK325AB7106[]MHP		35		X7R	10 μ	±10, ±20	10	150	2.5±0.30	*1, *2
TMK325AB7106 MHPR		25		X7R	10 μ	±10, ±20	10	150	2.5±0.30	*1, *2
TMK325 B7226 MHP		25		X7R	22 μ	±10, ±20	10	150	2.5±0.20	*1, *2
EMK325 B7226 ☐MHP		16		X7R	22 μ	±10, ±20	10	150	2.5±0.20	*1, *2
LMK325 B7226 MHP		10		X7R	22 μ	±10, ±20	10	150	2.5±0.20	*1, *2
JMK325 B7226 ☐ MHPR		6.3		X7R	22 μ	±10, ±20	10	150	2.5±0.20	*1, *2
JMK325 B7476∏MHPR		0.3		X7R	47 μ	±10, ±20	10	150	2.5±0.20	*1, *2

[Temperature Characteristic B7 : X7R] 1.9mm thickness(N)

Part number 1	Part number 2	Rated voltage [V]	Temperature characteristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Note
GMK325 B7225 NHT		35	X7R	2.2 μ	±10, ±20	3.5	200	1.9±0.20	*1, *2
GMK325 B7475 NHTR		30	X7R	4.7 μ	±10, ±20	10	150	1.9±0.20	*1, *2
TMK325 B7475 NHT		25	X7R	4.7 μ	±10, ±20	10	150	1.9±0.20	*1, *2
EMK325 B7475 NHT		16	X7R	4.7 μ	±10, ±20	3.5	150	1.9±0.20	*1, *2
EMK325 B7106[NHTR		10	X7R	10 μ	±10, ±20	10	150	1.9±0.20	*1, *2

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Multilayer Ceramic Capacitors

■PACKAGING

1 Minimum Quantity

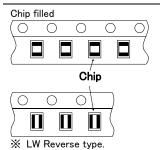
Taped package	TILL		0, 1, 1	F 3
Type(EIA)	Thick mm	code	Paper tape	uantity [pcs] Embossed tape
□MK021(008004)	0.125	K	- парет саре	50000
□VS021(008004)	0.123	IX		30000
☐MK042(01005)	0.2	C, D	_	40000
□VS042(01005)	0.2	С	_	40000
☐MK063(0201)	0.3	P,T	15000	_
□WK105(0204) ※	0.3	Р	10000	_
	0.13	Н	_	20000
DM(105(0400)	0.18	E	_	15000
☐MK105(0402) ☐MF105(0402)	0.2	С	20000	_
MF 105(0402)	0.3	Р	15000	_
	0.5	V	10000	_
□VK105(0402)	0.5	W	10000	_
□MK107(0603)	0.45	K	4000	_
□WK107(0306) ※	0.5	V	_	4000
□MF107(0603)	0.8	Α	4000	_
□VS107(0603)	0.7	С	4000	_
□MJ107(0603)	0.8	Α	3000	3000
□MK212(0805)	0.45	K	4000	
□WK212(0508) ※	0.85	D	4000	_
□MF212(0805)	1.25	G	_	3000
□VS212(0805)	0.85	D	4000	_
	0.85	D	4000	_
□MJ212(0805)	1.25	G	_	2000
	0.85	D	4000	_
□MK316(1206)	1.15	F	_	3000
□MF316(1206)	1.6	L	_	2000
	1.15	F	_	3000
□MJ316(1206)	1.6	L	_	2000
	0.85	D		
	1.15	F	1	
☐MK325(1210)	1.9	N	1 -	2000
□MF325(1210)	2.0max.	Y	1	
	2.5	M	_	1000
[] 1 1005(1015)	1.9	N	_	2000
□MJ325(1210)	2.5	М	_	500(T), 1000(P)
□MK432(1812)	2.5	М	_	500

Note:

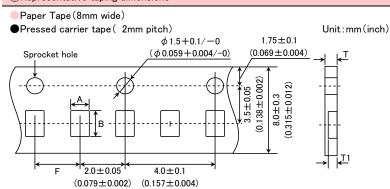
K LW Reverse type.

**No bottom tape for pressed carrier tape Card board carrier tape Top tape Base tape Sprocket hole Chip cavity Base tape Chip cavity

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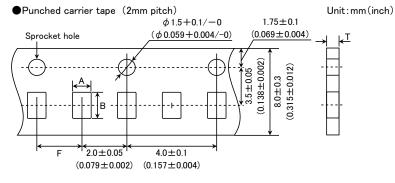
3 Representative taping dimensions



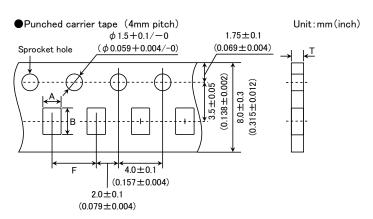
Type(EIA)	Chip	Cavity	Insertion Pitch	Tape Th	nickness
Type(EIA)	Α	В	F	Т	T1
□MK063(0201)	0.37	0.67		0.45max.	0.42max.
□WK105(0204) ※			2.0±0.05	0.45max.	0.42max.
□MK105(0402) (*1 C)	0.65	1.15	2.0±0.05	0.4max.	0.3max.
□MK105(0402) (*1 P)				0.45max.	0.42max.

Note *1 Thickness, C:0.2mm ,P:0.3mm. * LW Reverse type.

Unit:mm



Type(EIA)	Chip	Cavity	Insertion Pitch	Tape Thickness
Type(EIA)	Α	В	F	Т
☐MK105 (0402)				
☐MF105 (0402)	0.65	1.15	2.0 ± 0.05	0.8max.
□VK105 (0402)				
	•			Unit:mm

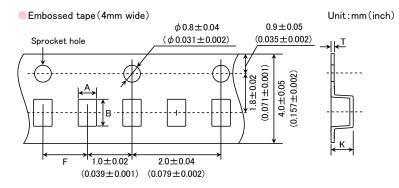


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Type(EIA)	Chip (Cavity	Insertion Pitch	Tape Thickness
Type(EIA)	Α	В	F	Т
☐MK107(0603)				
□WK107(0306) ※	1.0	1.8		1.1max.
☐MF107(0603)			40+01	
☐MK212(0805)	1.65	0.4	4.0±0.1	
□WK212(0508) ※	1.65	2.4		1.1max.
☐MK316(1206)	2.0	3.6		

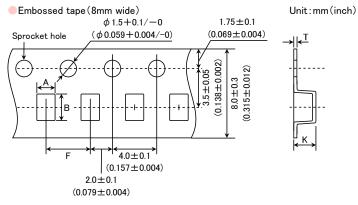
Note: Taping size might be different depending on the size of the product. X LW Reverse type.

Unit:mm



Type(EIA)	Chip (Cavity	Insertion Pitch	Tape Ti	nickness
Type(EIA)	Α	В	F	K	Т
☐MK021(008004)	0.135	0.27			
□VS021(008004)	0.135	0.27	1.0±0.02	0.5max.	0.25max.
☐MK042(01005)	0.23	0.43	1.0 ± 0.02	o.omax.	0.25max.
□VS042(01005)	0.23	0.43			

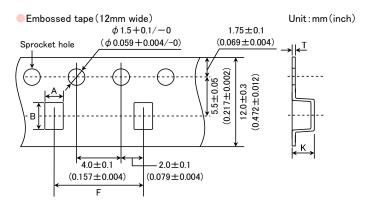
Unit:mm



Type(EIA)	Chip (Chip Cavity		Tape Thickness	
Type(EIA)	Α	В	F	K	Т
☐MK105(0402)	0.6	1.1	2.0±0.1	0.6max	0.2±0.1
□WK107(0306) ※	1.0	1.8		1.3max.	0.25±0.1
☐MK212(0805) ☐MF212(0805)	1.65	2.4			
☐MK316(1206) ☐MF316(1206)	2.0	3.6	4.0±0.1	4.0±0.1 3.4max.	0.6max.
☐MK325(1210) ☐MF325(1210)	2.8	3.6]		

Note: ※ LW Reverse type. Unit:mm

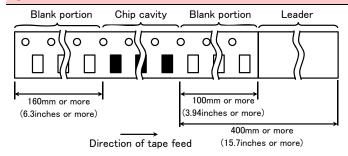
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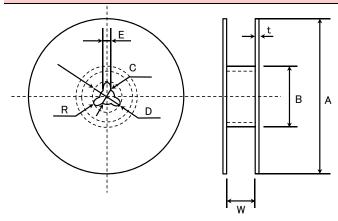
Type(EIA)	Chip (Cavity	Insertion Pitch	Tape Thickness	
	Α	В	F	K	Т
☐MK325(1210)	3.1	4.0	8.0±0.1	4.0max.	0.6max.
☐MK432(1812)	3.7	4.9	8.0±0.1	4.0max.	0.6max.

Unit:mm

4 Trailer and Leader



⑤Reel size



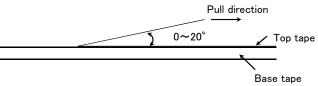
Α	В	С	D	E	R
ϕ 178 ± 2.0	<i>ф</i> 50min.	ϕ 13.0 \pm 0.2	ϕ 21.0 ± 0.8	2.0±0.5	1.0

	T	W
4mm wide tape	1.5max.	5±1.0
8mm wide tape	2.5max.	10±1.5
12mm wide tape	2.5max.	14±1.5

Unit:mm

6Top Tape Strength

The top tape requires a peel-off force of 0.1 to 0.7N in the direction of the arrow as illustrated below.



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Multilayer Ceramic Capacitors

■RELIABILITY DATA

	mperature Range	Standard					
	Temperature		-55 to +	−55 to +125°C			
Compensating(Class1)		High Frequency Type					
				Specification	Temperature Range)	
			BJ	В	−25 to +85°C		
pecified				X5R	-55 to +85°C		
/alue			B7	X7R	−55 to +125°C		
	High Permittivity (Class2)		C6	X6S	−55 to +105°C		
			C7	X7S	-55 to +125℃		
			D7	X7T	-55 to +125°C		
			LD(※)	X5R	−55 to +85°C		
			Note: 🔆	LD Low distortion hi	gh value multilayer ceran	nic capacito	
Storage Cor	nditions						
	T	Standard					
	Temperature Compensating(Class1)		−55 to +	-125°C			
	Compensating (Class I)	High Frequency Type					
				Specification	Temperature Range	÷	
			BJ	В	−25 to +85°C		
pecified			В	X5R	−55 to +85°C		
alue			B7	X7R	−55 to +125°C		
	High Permittivity (Class2))	C6	X6S	-55 to +105°C		
			C7	X7S	−55 to +125°C		
			D7	X7T	−55 to +125°C		
			LD(※)	X5R	−55 to +85°C		
			Note: 🔆	LD Low distortion hi	gh value multilayer ceran	nic capacit	
			•				
Rated Voltag	Υ <u>Α</u>						
Mateu Volta		0	50) (D.O. 05				
Specified	Temperature	Standard	50VDC, 25	VDC			
/alue	Compensating(Class1)	High Frequency Type	50VDC, 25VDC				
2.00	High Permittivity (Class2)		50VDC, 35	50VDC, 35VDC, 25VDC, 16VDC, 10VDC, 6.3VDC, 4VDC, 2.5VDC			
Withstanding	y Voltage (Between terminal	2)					
. withstanding	voltage (between terminal						
D	Temperature	Standard					
Specified	Compensating(Class1)	High Frequency Type	No breakd	own or damage			
'alue	High Permittivity (Class2)						
	, ,		ass 1		ass 2		
est	Applied voltage		volta×3		ass 2 oltage × 2.5		
ฮรเ	Applied voltage	Rated			ortage ^ Z.0		
	Duration		1 to 5 sec.				
lethods and emarks	Duration Charge/discharge currer			50mA max.			

Standard Temperature 10000 M Ω min. ${\sf Compensating}({\sf Class1})$ High Frequency Type Specified Value C \leq 0.047 μ F : 10000 M Ω min. High Permittivity (Class2) Note 1 C>0.047 μ F : 500M Ω • μ F : Rated voltage Test Applied voltage Methods and Duration : 60±5 sec. Remarks Charge/discharge current : 50mA max.

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6. Capacitance	(Tolerance)					
	Temperature	Standard	C □ U □ SL	0.2pF≦C≦5pF 0.2pF≦C≦10pF C>10pF	: ±0.25pF : ±0.5pF : ±5% or ±10%	
Specified Value	Specified Compensating(Class1) Value	High Frequency Type	СН	0.3pF≦C≦2pF C>2pF	: ±0.1pF : ±5%	
	High Permittivity (Class2)	BJ, B7, C6, C7, D7, LD($\overset{\cdot}{\times}$): $\pm 10\%$ or $\pm 20\%$ Note: $\overset{\cdot}{\times}$ LD Low distortion high value multilayer ceramic capacitor				
				s 1	Class 2	
.		Standard	t	High Frequency Type	C≦10 <i>µ</i> F	C>10 µF
Test Methods and	Preconditioning		None		Thermal treatment (a	t 150°C for 1hr) Note 2
Remarks	Measuring frequency		1MHz:	±10%	1kHz±10%	120±10Hz
Remarks	Measuring voltage Note		0.5 to 5	5Vrms	1±0.2Vrms	0.5±0.1rms
	Bias application				one	

Specified	Temperature		Standard		C < 30pF : Q ≥ 400 + 20C C ≥ 30pF : Q ≥ 1000 (C:Nominal capacitance)			
Value	Compensating(Class1)	High F	requency Type	Refer	to detailed specification			
	High Permittivity (Class2) Note 1			BJ, B7, C6, C7, D7: 2.5% max.				
			Class 1		Class 2			
			Standard		High Frequency Type	C≦10 µF	C>10 µF	
	Preconditioning		None		Thermal treatment (at 150°C for 1hr) Note 2			
Test	Measuring frequey		1MHz±10%		1GHz	1kHz±10%	120±10Hz	
Methods and	Measuring voltage Note 1		0.5 to 5Vrms		1±0.2Vrms	0.5±0.1Vrms		
Remarks	Bias application			None				
	High Frequency Type							
	Measuring equipment: HP4291A							
	Measuring jig : HP16192A							

			Temperature Characteristic [ppm/°C]			C] Tole	erance [ppm/°C]	
			C□:	0	CG,CH, CJ, (СК	G: ±30 H: ±60	
	Temperature Compensating(Class1)	Standard	U□ :	— 750	UJ, UK		J: ±120 K: ±250	
			SL :	+350 to −100	0			
		High Frequency Type	Tem	perature Charac	cteristic [ppm/°	C] Tole	Tolerance [ppm/°C]	
		riigii i requericy Type	C□:	0	CH		H: ±60	
Specified			Specification	Capacitance	Reference	Temperature Range		
Value				оростоиного	change	temperature	Tomporacaro riango	
		BJ	В	±10%	20°C	−25 to +85°C		
			60	X5R	±15%	25°C	-55 to +85°C	
	10 1 D 10 10 (O)		В7	X7R	±15%	25°C	−55 to +125°C	
	High Permittivity (Glass2,	High Permittivity (Class2)		X6S	±22%	25°C	−55 to +105°C	
			C7	X7S	±22%	25°C	−55 to +125°C	
			D7	X7S	+22/-33%	25°C	−55 to +125°C	
					±15%	25°C	−55 to +85°C	
			Note:	VID Low diete	rtion high value i	multilavar aaran	io consoiter	

Class 1

Capacitance at 20° C and 85° C shall be measured in thermal equilibrium, and the temperature characteristic shall be calculated from the following equation.

$$\frac{(C_{85}-C_{20})}{C_{20}\times\Delta T} \times 10^{6} (ppm/^{\circ}C) \qquad \Delta T = 65$$

Test Methods and Remarks Class 2

Capacitance at each step shall be measured in thermal equilibrium, and the temperature characteristic shall be calculated from the following equation

Step	В	X5R, X7R, X6S, X7S, X7T			
1	Minimum operating temperature				
2	20°C	25°C			
3	Maximum operating temperature				

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 $\frac{(C-C_2)}{C_2} \times 100(\%)$

C : Capacitance in Step 1 or Step 3

C2 : Capacitance in Step 2

9. Deflection				
	Temperature Compensating(Class1) Value	Standard	Appearance Capacitance change	: No abnormality : Within $\pm 5\%$ or ± 0.5 pF, whichever is larger.
Specified Value		High Frequency Type	Appearance Cpaitance change	: No abnormality : Within±0.5 pF
			Appearance	: No abnormality

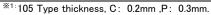
High Permittivity (Class2)

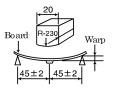
Capacitance change : Within ±12.5%(BJ, B7, C6, C7, D7, LD(※))

Note: XLD Low distortion high value multilayer ceramic capacitor

Test Methods and Remarks

	Multilayer Ceramic Capacitors				
	042, 063, ^{※1} 105 Type	The other types			
Board	Glass epoxy-resin substrate				
Thickness	0.8mm	1.6mm			
Warp	1mm (Soft Termination type:3mm)				
Duration	10 sec.				





(Unit: mm)

Capacitance measurement shall be conducted with the board bent

10. Body Stren	gth		
	Temperature	Standard	-
Specified Value	Compensating(Class1)	High Frequency Type	No mechanical damage.
Value	High Permittivity (Class2)		
Test Methods and Remarks	High Permittivity (Class2) High Frequency Type Applied force : 5N Duration : 10 sec. Pre ← A →		R0.5 Pressing Jig Chip A

11. Adhesive S	11. Adhesive Strength of Terminal Electrodes						
	Temperature	Standard		No terminal separation or its indication.			
Specified Value	Compensating(Class1)	High Frequency Type	No terminal separati				
Value	High Permittivity (Class2)						
	Multilayer C		ic Capacitors	Hooked jig			
Test		042, 063 Type	105 Type or more				
Methods and	Applied force	2N	5N	R=05 Doard			
Remarks	Duration	30±5	sec.] ←Chip			
				Chip Chip			

12. Solderabilit	у				
Specified Value	Temperature	Standard			
	Compensating(Class1)	High Frequency Type	At least 95% of terminal electrode is covered by new solder.		by new solder.
Value	High Permittivity (Class2))			
- .		Eutectic so	older	Lead-free solder	
Test	Solder type	H60A or H63A		Sn-3.0Ag-0.5Cu	
Methods and Remarks	Solder temperature	230±5°C		245±3°C	
Remarks	Duration		4±1	sec.	

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13. Resistance	to Soldering				
Specified Value	Temperature	Standard	Appearance Capacitance change Q Insulation resistance Withstanding voltage	: No abnormality : Within ±2.5% or ±0 : Initial value : Initial value (between terminals)	.25pF, whichever is larger. : No abnormality
	Compensating(Class1)	High Frequency Type	Appearance Capacitancecange Q Insulation resistance Withstanding voltage	: No abnormality : Within ±2.5% : Initial value : Initial value (between terminals)	: No abnormality
	High Permittivity (Class2) Note 1		Appearance Capactace change Dissipation factor Insulation resistance Withstanding voltage Note: **LD Low distort	: No abormality : Within ±7.5%(BJ, B' : Initial value : Initial value (between terminals): tion high value multilaye	No abnormality
		042, 063 Type	1	05 Type	
	Preconditioning		None		
	Preheating	150°C, 1 to 2 min.		0°C, 2 to 5 min. 00°C, 2 to 5 min.	
	Solder temp.		270±5°C		
	Duration		3±0.5 sec.		
Γest	Recovery	6 to 24 hrs	S (Standard condition) N	loe 5	
Methods and Remarks				Class 2	
		042,063 Type		07, 212 Type	316, 325 Type
	Preconditioning	. ,,,,		(at 150°C for 1 hr) No	
	Preheating	150°C, 1 to 2 min.	80 to 10	0°C, 2 to 5 min.	80 to 100°C, 5 to 10 min. 150 to 200°C, 5 to 10 min.
	Solder temp.			70±5°C	
	Duration			±0.5 sec.	
	Recovery			ndard condition)Note 5	i

14. Temperatur	re Cycle (Thermal Shock)						
	Temperature	Standard		Appearance Capacitance change Q Insulation resistance Withstanding voltage	: No abnormality : Within ±2.5% or ±0.25 : Initial value : Initial value (between terminals) : N	-	
Specified Value	Compensating(Class1)	High Frequency	[,] Туре	Appearance Capacitance change Q Insulation resistance Withstanding voltage	: No abnormality : Within ±0.25pF : Initial value : Initial value (between terminals) : N	o abnormality	
	High Permittivity (Class2) Note 1			Appearance Capacitance change Dissipation factor Insulation resistance Withstanding voltage Note: **LD Low distort	: No abnormality : Within ±7.5% (BJ, B7, : Initial value : Initial value (between terminals) : N ion high value multilayer c	o abnormality	
			C	class 1 Class 2		Class 2	
	Preconditioning	None			Thermal trea	tment (at 150°C for 1 hr) Note 2	
Test Methods and Remarks	1 cycle		Step 1 2 3 4	Minimum opera Normal to Maximum opera	ature (°C) Iting temperature Emperature ting temperature Emperature	Time (min.) 30 ± 3 $2 \text{ to } 3$ 30 ± 3 $2 \text{ to } 3$	
	Number of cycles				5 times		
	Recovery	6 to 24 hr	S (Stan	dard condition)Note 5	24±2 hrs (5	Standard condition)Note 5	

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15. Humidity (Steady State)				
	Temperature Compensating(Class1			: No abnormality : Within $\pm 5\%$ or $\pm 0.5 pF$, whichever is larger. : $C < 10 pF$: $Q \ge 200 + 10 C$ $10 \le C < 30 pF$: $Q \ge 275 + 2.5 C$ $C \ge 30 pF$: $Q \ge 350$ (C : Nominal capacitance) : $1000 \text{ M} \Omega \text{ min}$.	
Specified Value		High Frequency Type	Appearance Capacitance change Insulation resistance	No abnormality Within ± 0.5 pF, ± 1000 M Ω min.	
	High Permittivity (Cla	ass2) Note 1	Insulation resistance	: No abnormality : Within \pm 12.5% (BJ, B7, C6, C7, D7, LD($\stackrel{.}{\otimes}$)) : 5.0% max. (BJ, B7, C6, C7, D7, LD($\stackrel{.}{\otimes}$)) : 50 M $\Omega\mu$ F or 1000 M Ω whichever is smaller. on high value multilayer ceramic capacitor	
			ass 1	Class 2	
_		Standard	High Frequency Type		
Test	Preconditioning		one co L o°o	Thermal treatment (at 150°C for 1 hr) Note 2	
Methods and Remarks	Temperature	40±2°C	60±2°C	40±2°C 90 to 95%RH	
Remarks	Humidity Duration		95%R⊓ 4/−0 hrs	90 to 95%RH 500+24/-0 hrs	
	Recovery		ard condition)Note 5	24±2 hrs (Standard condition) Note 5	

16. Humidity Lo	pading			
Specified Value	Temperature	Standard	Appearance Capacitance change Q Insulation resistance	: No abnormality : Within $\pm 7.5\%$ or ± 0.75 pF, whichever is larger. : C < 30 pF : Q $\ge 100 + 10$ C/3 C ≥ 30 pF : Q ≥ 200 (C:Nominal capacitance) : 500 M Ω min.
	Compensating(Class1)	High Frequency Type	Appearance : No abnormality Capacitance change : C≦2pF:Within ±0.4 pF C>2pF:Within ±0.75 pF (C:Nominal capacitance) Insulation resistance : 500 M Ω min.	
	High Permittivity(Class2) Note 1	Appearance Capacitance change Dissipation factor Insulation resistance Note: **LD Low distort	: No abnormality : Within \pm 12.5% (BJ, B7, C6, C7, D7, LD($\%$)) : 5.0% max. (BJ, B7, C6, C7, D7, LD($\%$)) : 25 M $\Omega\mu$ F or 500 M Ω whichever is smaller. cion high value multilayer ceramic capacitor
		C	Class 1	Class 2
		Standard	High Frequency Typ	pe All items
	Preconditioning		None	Voltage treatment (Rated voltage are applied for 1 hour at 40°C) Note 3
Test	Temperature	40±2°C	60±2°C	40±2°C
Methods and	Humidity	90 t	:o 95%RH	90 to 95%RH
Remarks	Duration	500+	24/-0 hrs	500+24/-0 hrs
	Applied voltage	Rate	d voltage	Rated voltage
	Charge/discharge current	50r	mA max.	50mA max.
	Recovery	6 to 24 hrs (Stan	dard condition)Note 5	24±2 hrs(Standard condition) Note 5

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17. High Tempe	erature Loading					
Specified Value	Temperature Compensating(Class1)	Appearance Capacitance change Q Insulation resistance		: C<10pF: Q≧200+10C 10≦C<30pF:Q≧275+2.5C C≧30pF: Q≧350(C:Nominal capacitance)		
		High Frequency Type	Appearance : No abnormality Gapacitance change : Within $\pm 3\%$ or ± 0.3 pF, whichever is larger. Insulation resistance : $1000 \text{ M}\Omega$ min.			is larger.
	High Permittivity(Class2) Note 1	Appearance Capacitance change Dissipation factor Insulation resistance Note: **LD Low dis*	: 5.0% max.(BJ, E	(BJ, B7, C6, C7, D 37, C6, C7, D7, LDG 00 MΩ whichever is tilayer ceramic capa	※)) s smaller.
		Class 1		Class 2		
		Standard High Frequency Type		BJ, LD(※)	C6	B7, C7, D7
	Preconditioning	None		Voltage treatment (Twice the rated voltage shall be applied for 1 hour at 85°C, 105°C or 125°C) Note 3, 4		
Test	Temperature	Maximum operati	ng temperature	Maximum operating temperature		
Methods and	Duration	1000+48	/-0 hrs		1000 + 48 / -0 hr	'S
Remarks	Applied voltage	Rated vol	ltage × 2	Rated voltage × 2 Note 4		
	Charge/discharge current	50mA	max.	50mA max.		
	Recovery	6 to 24hr(Standard	condition) Note 5	24±2 hrs(Standard condition)Note 5		
			Note	*LD Low distortion	n high value multil	ayer ceramic capacitor

Note 1 The figures indicate typical specifications. Please refer to individual specifications in detail.

- Note 2 Thermal treatment : Initial value shall be measured after test sample is heat-treated at $150 \pm 0/-10^{\circ}$ C for an hour and kept at room temperature for 24 ± 2 hours.
- Note 3 Voltage treatment: Initial value shall be measured after test sample is voltage—treated for an hour at both the temperature and voltage specified in the test conditions, and kept at room temperature for 24±2hours.
- Note 4 150% of rated voltage is applicable to some items. Please refer to their specifications for further information.
- Note 5 Standard condition: Temperature: 5 to 35°C, Relative humidity: 45 to 85 % RH, Air pressure: 86 to 106kPa When there are questions concerning measurement results, in order to provide correlation data, the test shall be conducted under the following condition.

 Temperature: 20±2°C, Relative humidity: 60 to 70 % RH, Air pressure: 86 to 106kPa Unless otherwise specified, all the tests are conducted under the

"standard condition".

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Precautions on the use of Multilayer Ceramic Capacitors

■PRECAUTIONS

1. Circuit Design

- ◆Verification of operating environment, electrical rating and performance
 - A malfunction of equipment in fields such as medical, aerospace, nuclear control, etc. may cause serious harm to human life or have severe social ramifications.

Therefore, any capacitors to be used in such equipment may require higher safety and reliability, and shall be clearly differentiated from them used in general purpose applications.

Precautions

- ◆Operating Voltage (Verification of Rated voltage)
 - 1. The operating voltage for capacitors must always be their rated voltage or less.
 - If an AC voltage is loaded on a DC voltage, the sum of the two peak voltages shall be the rated voltage or less.
 - For a circuit where an AC or a pulse voltage may be used, the sum of their peak voltages shall also be the rated voltage or less.
 - 2. Even if an applied voltage is the rated voltage or less reliability of capacitors may be deteriorated in case that either a high frequency AC voltage or a pulse voltage having rapid rise time is used in a circuit.

2. PCB Design

Precautions

Technical considerations

- ◆Pattern configurations (Design of Land-patterns)
 - 1. When capacitors are mounted on PCBs, the amount of solder used (size of fillet) can directly affect the capacitor performance. Therefore, the following items must be carefully considered in the design of land patterns:
 - (1) Excessive solder applied can cause mechanical stresses which lead to chip breaking or cracking. Therefore, please consider appropriate land-patterns for proper amount of solder.
 - (2) When more than one component are jointly soldered onto the same land, each component's soldering point shall be separated by solder-resist.
- ◆Pattern configurations (Capacitor layout on PCBs)

After capacitors are mounted on boards, they can be subjected to mechanical stresses in subsequent manufacturing processes (PCB cutting, board inspection, mounting of additional parts, assembly into the chassis, wave soldering of the boards, etc.). For this reason, land pattern configurations and positions of capacitors shall be carefully considered to minimize stresses.

◆Pattern configurations (Design of Land-patterns)

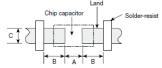
The following diagrams and tables show some examples of recommended land patterns to prevent excessive solder amounts.

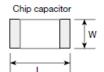
- (1) Recommended land dimensions for typical chip capacitors
- Multilayer Ceramic Capacitors : Recommended land dimensions (unit: mm)

Wave-soldering

Type		107	212	316	325
6:20	Sing L 1.6		2.0	3.2	3.2
Size	Size W 0.8		1.25	1.6	2.5
A	4	0.8 to 1.0	1.0 to 1.4	1.8 to 2.5	1.8 to 2.5
В		0.5 to 0.8	0.8 to 1.5	0.8 to 1.7	0.8 to 1.7
С		0.6 to 0.8	0.9 to 1.2	1.2 to 1.6	1.8 to 2.5

Land patterns for PCBs





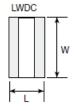
Reflow-soldering

Ту	ре	042	063	105	107	212	316	325	432
Size	L	0.4	0.6	1.0	1.6	2.0	3.2	3.2	4.5
Size	W	0.2	0.3	0.5	0.8	1.25	1.6	2.5	3.2
,	4	0.15 to 0.25	0.20 to 0.30	0.45 to 0.55	0.8 to 1.0	0.8 to 1.2	1.8 to 2.5	1.8 to 2.5	2.5 to 3.5
I	3	0.15 to 0.20	0.20 to 0.30	0.40 to 0.50	0.6 to 0.8	0.8 to 1.2	1.0 to 1.5	1.0 to 1.5	1.5 to 1.8
()	0.15 to 0.30	0.25 to 0.40	0.45 to 0.55	0.6 to 0.8	0.9 to 1.6	1.2 to 2.0	1.8 to 3.2	2.3 to 3.5

 ${\tt Note:} Recommended \ land \ size \ might \ be \ different \ according \ to \ the \ allowance \ of \ the \ product.$

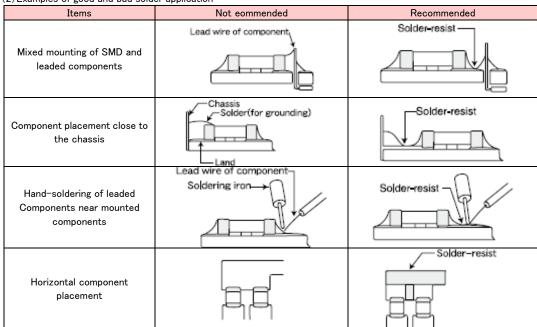
●LWDC: Recommended land dimensions for reflow-soldering (unit: mm)

(dilic.	/			
Туре		105	107	212
C: L		0.52	0.8	1.25
Size	W	1.0	1.6	2.0
-	٩	0.18 to 0.22	0.25 to 0.3	0.5 to 0.7
В		0.2 to 0.25	0.3 to 0.4	0.4 to 0.5
С		0.9 to 1.1	1.5 to 1.7	1.9 to 2.1



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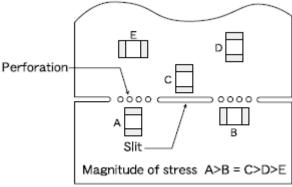
(2) Examples of good and bad solder application



- ◆Pattern configurations (Capacitor layout on PCBs)
 - 1-1. The following is examples of good and bad capacitor layouts; capacitors shall be located to minimize any possible mechanical stresses from board warp or deflection.

Items	Not recommended	Recomm	mended
Deflection of board			Place the product at a right angle to the direction of the anticipated mechanical stress.

1-2. The amount of mechanical stresses given will vary depending on capacitor layout. Please refer to diagram below.



3. Mounting

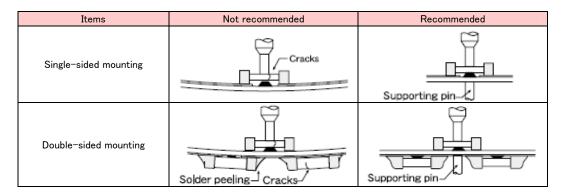
considerations

1-3. When PCB is split, the amount of mechanical stress on the capacitors can vary according to the method used. The following methods are listed in order from least stressful to most stressful: push-back, slit, V-grooving, and perforation. Thus, please consider the PCB, split methods as well as chip location.

◆Adjustment of mounting machine 1. When capacitors are mounted on PCB, excessive impact load shall not be imposed on them. 2. Maintenance and inspection of mounting machines shall be conducted periodically. Precautions ◆Selection of Adhesives 1. When chips are attached on PCBs with adhesives prior to soldering, it may cause capacitor characteristics degradation unless the following factors are appropriately checked: size of land patterns, type of adhesive, amount applied, hardening temperature and hardening period. Therefore, please contact us for further information. ◆Adjustment of mounting machine 1. When the bottom dead center of a pick-up nozzle is too low, excessive force is imposed on capacitors and causes damages. To avoid this, the following points shall be considerable. Technical

- - (1) The bottom dead center of the pick-up nozzle shall be adjusted to the surface level of PCB without the board deflection.
 - (2) The pressure of nozzle shall be adjusted between 1 and 3 N static loads.
 - (3) To reduce the amount of deflection of the board caused by impact of the pick-up nozzle, supporting pins or back-up pins shall be used on the other side of the PCB. The following diagrams show some typical examples of good and bad pick-up nozzle placement:

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2. As the alignment pin is worn out, adjustment of the nozzle height can cause chipping or cracking of capacitors because of mechanical impact on the capacitors.

To avoid this, the monitoring of the width between the alignment pins in the stopped position, maintenance, check and replacement of the pin shall be conducted periodically.

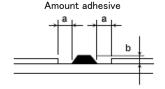
Selection of Adhesives

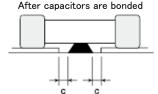
Some adhesives may cause IR deterioration. The different shrinkage percentage of between the adhesive and the capacitors may result in stresses on the capacitors and lead to cracking. Moreover, too little or too much adhesive applied to the board may adversely affect components. Therefore, the following precautions shall be noted in the application of adhesives.

- (1) Required adhesive characteristics
 - a. The adhesive shall be strong enough to hold parts on the board during the mounting & solder process.
 - b. The adhesive shall have sufficient strength at high temperatures.
 - c. The adhesive shall have good coating and thickness consistency.
 - d. The adhesive shall be used during its prescribed shelf life.
 - e. The adhesive shall harden rapidly.
 - f. The adhesive shall have corrosion resistance.
 - g. The adhesive shall have excellent insulation characteristics.
 - h. The adhesive shall have no emission of toxic gasses and no effect on the human body.
- (2) The recommended amount of adhesives is as follows;

[Recommended condition]

Figure	212/316 case sizes as examples			
a 0.3mm min				
b	100 to 120 μm			
С	Adhesives shall not contact land			





4. Soldering

Precautions

◆Selection of Flux

Since flux may have a significant effect on the performance of capacitors, it is necessary to verify the following conditions prior to use;

- (1) Flux used shall be less than or equal to 0.1 wt% (in Cl equivalent) of halogenated content. Flux having a strong acidity content shall not be applied.
- (2) When shall capacitors are soldered on boards, the amount of flux applied shall be controlled at the optimum level.
- (3) When water-soluble flux is used, special care shall be taken to properly clean the boards.

◆ Soldering

Temperature, time, amount of solder, etc. shall be set in accordance with their recommended conditions.

Sn-Zn solder paste can adversely affect MLCC reliability.

Please contact us prior to usage of Sn-Zn solder.

◆Selection of Flux

- 1-1. When too much halogenated substance (Chlorine, etc.) content is used to activate flux, or highly acidic flux is used, it may lead to corrosion of terminal electrodes or degradation of insulation resistance on the surfaces of the capacitors.
- 1-2. Flux is used to increase solderability in wave soldering. However if too much flux is applied, a large amount of flux gas may be emitted and may adversely affect the solderability. To minimize the amount of flux applied, it is recommended to use a flux-bubbling system.
- 1-3. Since the residue of water-soluble flux is easily dissolved in moisture in the air, the residues on the surfaces of capacitors in high humidity conditions may cause a degradation of insulation resistance and reliability of the capacitors. Therefore, the cleaning methods and the capability of the machines used shall also be considered carefully when water-soluble flux is used.

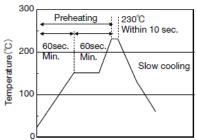
Technical considerations

◆ Soldering

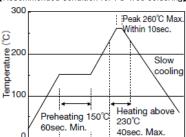
- · Ceramic chip capacitors are susceptible to thermal shock when exposed to rapid or concentrated heating or rapid cooling.
 - Therefore, the soldering must be conducted with great care so as to prevent malfunction of the components due to excessive thermal shock
 - Preheating: Capacitors shall be preheated sufficiently, and the temperature difference between the capacitors and solder shall be within 100 to 130°C.
- \cdot Cooling : The temperature difference between the capacitors and cleaning process shall not be greater than $100^{\circ}\text{C}.$
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[Reflow soldering]

[Recommended conditions for eutectic soldering]

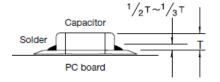


[Recommended condition for Pb-free soldering]



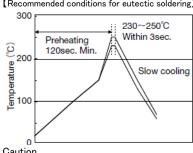
Caution

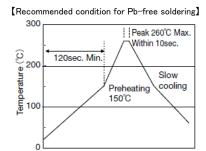
- \bigcirc The ideal condition is to have solder mass (fillet) controlled to 1/2 to 1/3 of the thickness of a capacitor.
- ②Because excessive dwell times can adversely affect solderability, soldering duration shall be kept as close to recommended times as possible.
- 3 Allowable number of reflow soldering: 2 times max.



[Wave soldering]

[Recommended conditions for eutectic soldering]



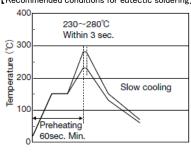


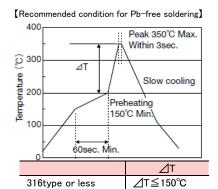
Caution

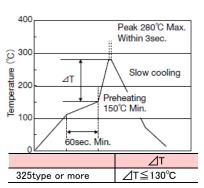
- ①Wave soldering must not be applied to capacitors designated as for reflow soldering only.
- ②Allowable number of wave soldering: 1 times max.

[Hand soldering]

[Recommended conditions for eutectic soldering]







Caution

- ①Use a 50W soldering iron with a maximum tip diameter of 1.0 mm.
- 2)The soldering iron shall not directly touch capacitors.
- 3Allowable number of hand soldering: 1 times max.

5. Cleaning

Precautions

♦Cleaning conditions

- 1. When PCBs are cleaned after capacitors mounting, please select the appropriate cleaning solution in accordance with the intended use of the cleaning. (e.g. to remove soldering flux or other materials from the production process.)
- 2. Cleaning condition shall be determined after it is verified by using actual cleaning machine that the cleaning process does not affect capacitor's characteristics.

Technical considerations

- 1. The use of inappropriate cleaning solutions can cause foreign substances such as flux residue to adhere to capacitors or deteriorate their outer coating, resulting in a degradation of the capacitor's electrical properties (especially insulation resistance).
- 2. Inappropriate cleaning conditions (insufficient or excessive cleaning) may adversely affect the performance of the capacitors. In the case of ultrasonic cleaning, too much power output can cause excessive vibration of PCBs which may lead to the cracking of capacitors or the soldered portion, or decrease the terminal electrodes' strength. Therefore, the following conditions shall be carefully checked;

20 W/l or less Ultrasonic output: Ultrasonic frequency: 40 kHz or less Ultrasonic washing period: 5 min. or less

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6. Resin coating and mold 1. With some type of resins, decomposition gas or chemical reaction vapor may remain inside the resin during the hardening period or while left under normal storage conditions resulting in the deterioration of the capacitor's performance. 2. When a resin's hardening temperature is higher than capacitor's operating temperature, the stresses generated by the excessive heat may lead to damage or destruction of capacitors.

The use of such resins, molding materials etc. is not recommended.

Please check the guide regarding precautions for deflection test, soldering by spot heat, and so on.

7. Handling Splitting of PCB 1. When PCBs are split after components mounting, care shall be taken so as not to give any stresses of deflection or twisting to the board. 2. Board separation shall not be done manually, but by using the appropriate devices. Mechanical considerations Be careful not to subject capacitors to excessive mechanical shocks. (1) If ceramic capacitors are dropped onto a floor or a hard surface, they shall not be used. (2) Please be careful that the mounted components do not come in contact with or bump against other boards or components.

8. Storage conditions	
Precautions	 ♦ Storage 1. To maintain the solderability of terminal electrodes and to keep packaging materials in good condition, care must be taken to control temperature and humidity in the storage area. Humidity should especially be kept as low as possible. • Recommended conditions Ambient temperature: Below 30°C Humidity: Below 70% RH The ambient temperature must be kept below 40°C. Even under ideal storage conditions, solderability of capacitor is deteriorated as time passes, so capacitors shall be used within 6 months from the time of delivery. • Ceramic chip capacitors shall be kept where no chlorine or sulfur exists in the air. The capacitance values of high dielectric constant capacitors will gradually decrease with the passage of time, so care shall be taken to design circuits. Even if capacitance value decreases as time passes, it will get back to the initial value by a heat treatment at 150°C for 1hour.
Technical considerations	If capacitors are stored in a high temperature and humidity environment, it might rapidly cause poor solderability due to terminal oxidation and quality loss of taping/packaging materials. For this reason, capacitors shall be used within 6 months from the time of delivery. If exceeding the above period, please check solderability before using the capacitors.
*RCR-2335B(S	Safety Application Guide for fixed ceramic capacitors for use in electronic equipment) is published by JEITA.

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